



IFW 3724
511.40998X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: N. KOYAMA et al.
Serial No.: 10/018,188
Filed: DECEMBER 18, 2001
For: CMP ABRASIVE, METHOD FOR POLISHING SUBSTRATE
AND METHOD FOR MANUFACTURING SEMICONDUCTOR
DEVICE USING THE SAME, AND ADDITIVE FOR CMP
ABRASIVE
Group AU: 3724
Examiner: Timothy V. Eley
Confirm. No.: 7930

AMENDMENT

Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

March 12, 2007

Sir:

In response to the Office Action mailed September 11, 2006, the period for response having been extended for three (3) months by the attached Petition for Extension of Time, please amend the above-identified application as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the Amendments.